



<b>Title of Change:</b>	WLP fab site change from Gunma, Japan to Niigata, Japan	
<b>Proposed first ship date:</b>	15 February 2016	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Akira.Yoneyama@onsemi.com">Akira.Yoneyama@onsemi.com</a>	
<b>Samples:</b>	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or <a href="mailto:Makoto.Nakaoka@onsemi.com">Makoto.Nakaoka@onsemi.com</a>	
<b>Type of notification:</b>	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact &lt;PCN.Support@onsemi.com&gt;.</p>	
<b>Change Part Identification:</b>	Product lots will be identified through a date code marked on the parts	
<b>Change category(s):</b> <input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change	<input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
<b>Sites Affected:</b> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	<u>Site 1</u> ON Niigata, Japan	<u>Site 2</u>
<b>Description and Purpose:</b> To continuously supply products and increase our supply capacity to support increased demand, the Wafer level package location will move from Gunma, Japan to Niigata, Japan. Most equipment and personnel will be transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified. Neither change in electrical characteristics, nor product reliability is expected.		

**Qualification Plan:**

Estimated date for qualification completion: 13 November 2015

**IC Reliability Plan****1.0****REFERENCE DOCUMENTS:** 12MSB17722C - Product Reliability Qualification Process Specification**2.0****WLP/FLIP Reliability Plan**

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**3.0**

Package	WLCSP179 WLCSP36 WLFCP6	Wafer Fab Site	Niigata
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**4.0****RELIABILITY TESTING REQUIREMENTS**

Test	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
HTOL	TJ ~ 150°C, for 1008 hrs	Test @ Room	77	3	231	
HTSL	150°C for 1008 hrs	Test @ Room	77	3	231	
THB	85°C/85% RH for 1008 hrs	Test @ Room	77	3	231	
TC	-40°C to +125°C for 500 cycles	Test @ Room	77	3	231	

Samples should be available after completion of Qualification.

**List of affected Standard Parts:**

LE2464CXATBG